

WHAT IS CLAIMED IS:

1. A process for manufacturing a flexible printed wiring board, comprising forming a resin coating at least on a metal bump on a metal film having said metal bump,
5 pressing said resin coating on said metal bump, and then etching said resin coating to expose the surface of said metal bump.

- 10 2. A process for manufacturing a flexible printed wiring board according to Claim 1 wherein said resin coating is formed on said metal bump and on said metal film.

- 15 3. A process for manufacturing a flexible printed wiring board according to Claim 2 wherein said resin coating comprises a lower thermosetting resin coating and an upper thermoplastic resin coating formed on the surface of said lower resin coating.

- 20 4. A process for manufacturing a flexible printed wiring board according to Claim 2 wherein a pressure is applied on said metal bump after a resist film resistant to etching with a chemical for etching said resin coating is formed on said resin coating.

- 25 5. A process for manufacturing a flexible printed wiring

board according to Claim 3 wherein a pressure is applied on said metal bump after a resist film resistant to etching with a chemical for etching said upper thermoplastic resin coating is formed on said upper 5 thermoplastic resin coating.

6. A process for manufacturing a flexible printed wiring board according to Claim 2 wherein said metal bump is formed by forming a photosensitive mask film on the 10 surface of said metal film, then patterning said mask film by exposure and development, and depositing a metal by plating on the surface of said metal film exposed at the opening of said mask film.

15 7. A process for manufacturing a flexible printed wiring board according to Claim 3 wherein said metal bump is formed by forming a photosensitive mask film on the 20 surface of said metal film, then patterning said mask film by exposure and development, and depositing a metal by plating on the surface of said metal film exposed at the opening of said mask film.

25 8. A process for manufacturing a flexible printed wiring board according to Claim 4 wherein said metal bump is formed by forming a photosensitive mask film on the

surface of said metal film, then patterning said mask film by exposure and development, and depositing a metal by plating on the surface of said metal film exposed at the opening of said mask film.

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9. A process for manufacturing a flexible printed wiring board according to Claim 5 wherein said metal bump is formed by forming a photosensitive mask film on the surface of said metal film, then patterning said mask film by exposure and development, and depositing a metal by plating on the surface of said metal film exposed at the opening of said mask film.

10. A process for manufacturing a flexible printed wiring board according to Claim 5 wherein said metal bump is formed by forming a photosensitive mask film on the surface of said metal film, then patterning said mask film by exposure and development, and depositing a metal by plating on the surface of said metal film exposed at the opening of said mask film.

10. A process for manufacturing a flexible printed wiring board according to Claim 2 wherein said pressing of said metal bump comprises at least rotating a roller against said resin coating.

15. A process for manufacturing a flexible printed wiring board according to Claim 2 wherein said pressing of said metal bump comprises at least rotating a roller against said resin coating.

20. A process for manufacturing a flexible printed wiring board according to Claim 4 wherein said pressing

of said metal bump comprises at least rotating a roller against said resin coating.

13. A process according for manufacturing a flexible
5 printed wiring board to Claim 5 wherein said pressing of
said metal bump comprises at least rotating a roller
against said resin coating.

10 14. A process for manufacturing a flexible printed
wiring board according to Claim 10 wherein said roller
is heated during said pressing.

15 15. A process for manufacturing a flexible printed
wiring board according to Claim 11 wherein said roller
15 is heated during said pressing.

16. A process for manufacturing a flexible printed
wiring board according to Claim 12 wherein said roller
is heated during said pressing.

20 17. A process for manufacturing a flexible printed
wiring board according to Claim 13 wherein said roller
is heated during said pressing.

25 18. A process for manufacturing a flexible printed

wiring board according to Claim 2 wherein a polyamic acid is used as a material for said resin coating.

19. A process for manufacturing a flexible printed
5 wiring board according to Claim 3 wherein a polyamic acid is used as a material for said resin coating.

20. A process for manufacturing a flexible printed
wiring board according to Claim 4 wherein a polyamic
10 acid is used as a material for said resin coating.

21. A process for manufacturing a flexible printed
wiring board according to Claim 5 wherein a polyamic acid is used as a material for said upper thermoplastic
15 resin coating and/or said lower thermosetting resin coating.

22. A flexible printed wiring board comprising a metal
film, a resin coating on said metal film, and a metal
20 bump located in an opening formed in said resin coating,
connected at its bottom face to said metal film and
having a height greater than the thickness of said resin
coating, wherein said resin coating is removed by
etching at least at the portion located at an end of
25 said metal bump to expose the end of said metal bump

from the surface of said resin coating.

23. A flexible printed wiring board according to Claim
22 wherein said metal film is patterned in a
5 predetermined form.

24. A flexible printed wiring board according to claim
23 wherein an electric device is mounted on said
flexible printed wiring board and a bonding pad of said
10 electric device is connected with the end of said metal
bump.